

Description

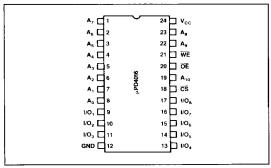
The $\mu PD4016$ is a 16,384-bit static Random-access Memory device organized as 2,048 words by 8 bits. Using a scaled NMOS technology, its design provides the ease-of-use features associated with nonclocked static memories. The $\mu PD4016$ has a three-state output and offers a standby mode with an attendant 75% savings in power consumption. It features equal access and cycle times and provides an output enable function that eliminates the need for external bus buffers. The $\mu PD4016$ is packaged in a 600-mil-wide standard 24-pin dual-in-line package which is plug-compatible with 16K EPROMS .

Features

2.2.0
Scaled NMOS technology
Completely static memory: no clock, no refresh
Equal access and cycle times
Single +5V power supply
Automatic power-down
All inputs and outputs directly TTL-compatible
Common I/O capability
OE eliminates need for external bus buffers
Three-state outputs
Plug-compatible with 16K 5V EPROMS (600 mil)
Low power dissipation in standby mode
Available in a standard 24-pin dual-in-line package
(600-mil width)
4 performance ranges:

	<u> </u>	R/W	Power Supply				
Device	Access Time	Cycle Time	Active	Standby			
μPD4016C-1	250ns	250ns	60mA	15mA			
μPD4016C-2	200ns	200ns	60mA	15mA			
μPD4016C-3	150ns	150ns	60mA	15mA			
μPD4016C-5	120ns	120ns	60mA	15mA			

Pin Configuration



Pin Identification

	Pin	Description
No.	Symbol	Description
1-8, 22, 23	A ₀ -A ₁₀	Address Inputs
9-11, 13-17	I/O ₁ -I/O ₈	Data Input/Output
12	GND	Ground
18	CS	Chip Select
20	ŌE	Output Enable
21	WE	Write Enable
24	V _{CC}	+ 5V Power Supply

Truth Table

CS	ŌĒ	WE	Mode	I/O	Power
Н	х	X	Not Selected	High-Z	Standby
L	L	н	Read	D _{OUT}	Active
L	н	L	Write	D _{IN}	Active
L	L	L	Write	D _{IN}	Active

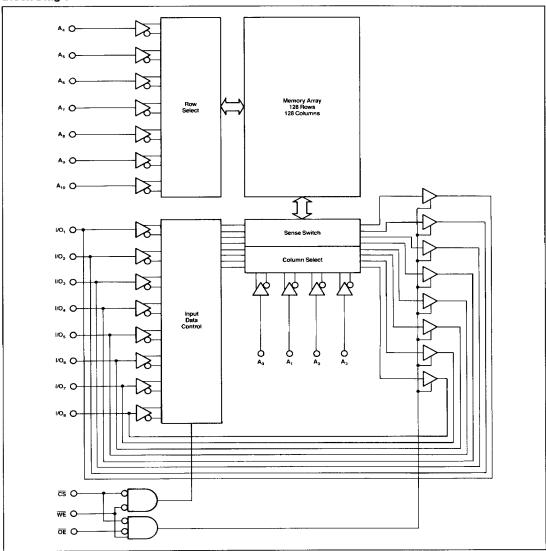
Absolute Maximum Ratings*

Temperature Under Bias	-10°C to +85°C
Storage Temperature, T _{ST}	-55°C to +125°C
Voltage on any Pin with Respect to Ground	-1.5V to +7V
DC Output Current, I _O	20mA
Power Dissipation, Po	1W

*COMMENT: Exposing the device to stresses above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational sections of this specification. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Block Diagram





Capacitance ①

T_A = 25°C; f = 1MHz

	-		Limits			Test
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Input Capacitance	C _{IN}			5	рF	V _{IN} = aV
I/O Capacitance	Cia			7	рF	$V_{iO} = 0V$

Note: 1 This parameter is sampled and not 100% tested.

DC Characteristics

 $T_A = 0$ °C to +70°C; $V_{CC} = 5V \pm 10\%$

			Limits		_	Test
Parameter	Symbol	Min	Тур	Max	Unit	Conditions ①
Input Leakage Current	l _U			10	μ Α	V _{CC} = Max V _{IN} = GND to V _{CC}
Output Leakage Current	I _{LO}			10	μА	$V_{CC} = Max; \overline{CS} = V_1$ $V_{OUT} = GND to V_{CC}$
Operating Current	Icc			60	mA	V _{CC} = Max; CS = V _i (outputs open)
Standby Current	I _{SB}			15	mA	V _{CC} = Min to Max; CS = V _{IH}
Input Low Voltage	VIL	- 1.5		0.8	٧	
Input High Voltage	VIH	2.0		6.0	٧	
Output Low Voltage	VoL			0.4	v	I _{OL} = 4mA
Output High Voltage	V _{OH}	2.4			V	I _{OH} = 1mA
Output Short-circuit Current	los		70		mA	$V_{OUT} = GND to V_{CC}$
Note: 1 Input pulse le			8V to 2.2	2V		
Input timing re	eference level	ls: 1.	5V			
Output timing	reference lev	refs: 1.	5 V			

Figure 1. Loading Conditions Test Circuit

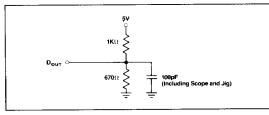
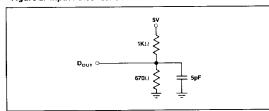


Figure 2. Input Pulse Test Circuit



AC Characteristics

 $T_A = 0$ °C to +70°C; $V_{CC} = 5V \pm 10$ % **Read Cycle**

					Limi	ts ①					
		4016-5		4016-3		4016-2		4016-1		•	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Read Cycle Time	1 _{RC}	120		150		200		250		ns	2
Address Access Time	t _{AA}		120		150		200		250	ns	
Chip Select Access Time	tacs		120		150		200		250	ns	3
Output Hold from Address Change	t _{OH}	10		10		10		10		ns	
Chip Selection to Output in Low-Z	t _{LZ}	10		10		10		10		ns	4 9
Chip Deselection to Output in High-Z	t _{HZ}		45		50		60		80	ns	4 5
Output Enable to Output Valid	t _{OE}		50		70		90		110	ns	
Output Enable to Output in Low-Z	t _{OLZ}	10		10		10		10		ns	4 (
Output Disable to Output in High-Z	t _{OHZ}		45		50		60		80	ns	4 5
Chip Selection to Power-up Time	t _{PU}	0		0		0		0		ns	(5)
Chip Deselection to Pawer-down Time	t _{PD}		60		70		90		110	ns	(§)

Write Cycle

			Limits ①								
		401	6-5	40	4016-3		6-2	4016-1		-	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	twc	120		150		200		250		ns	
Chip Selection to End of Write	t _{cw}	90		120		160		200		ns	
Address Valid to End of Write	taw	80		90		120		150		ns	
Address Set-up Time	tas	0		0		0		0		ns	
Write Pulse Width	twp	70		80		100		130		ns	6
Write Recovery Time	t _{WR}	10		10		10		10		ns	
Data Valid to End of Write	t _{DW}	45		50		60		80		nş	
Data Hold Time	t _{DH}	0		0		0		0		ns	
Write Enabled to Output in High-Z	twz		45		50		60		80	ns	(§) (T)
Output Active from End of Write	tow	10		10		10		10		ns	⑤ ⑦

- Notes: See Part No. Package Width table below
 Alf read cycle timings are referenced from the last valid address to the first transition address.
 Address valid prior to or coincident with CS transition low.
 Transition is measured 200mV from sleady-state voltage with specified load of Figure 1.
 This parameter is sampled and not 100% tested.
 If CS and DE are both low before write enabled, type—tyz—type.
 Transition is measured + 200mV from sleady-state voltage with specified load of Figure 2.

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Timing Waveforms

